TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20190910002
Datasheet for TMP116, TMP116N
Information Only

Date: September 16, 2019
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN team (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TMP116AIDRVR	null
TMP116AIDRVT	null
TMP116NAIDRVR	null
TMP116NAIDRVT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190910002	**PCN Date:**	Sept. 16, 2019
Title:	Datasheet for TMP116, TMP116N☐		
Customer Contact:	[PCN Manager]()	**Dept:**	Quality Services

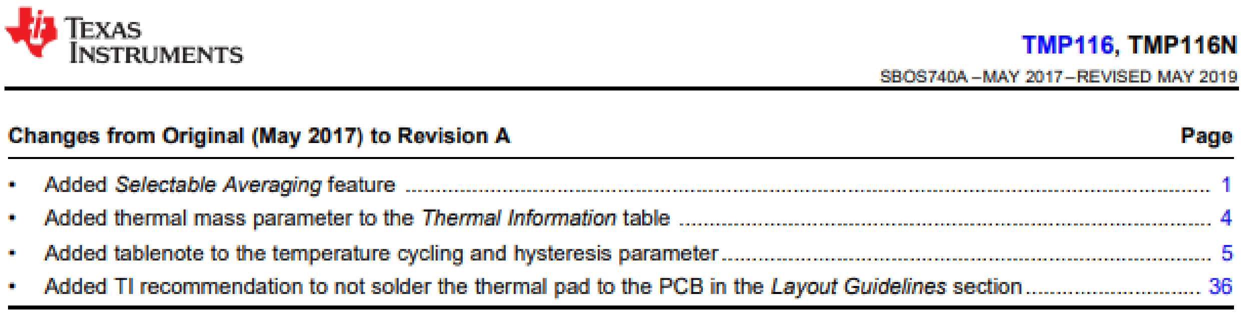
Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.



TEXAS INSTRUMENTS

TMP116, TMP116N

SBOS740A – MAY 2017 – REVISED MAY 2019

Changes from Original (May 2017) to Revision A	**Page**
- Added *Selectable Averaging* feature	1
- Added thermal mass parameter to the *Thermal Information* table	4
- Added tablenote to the temperature cycling and hysteresis parameter	5
- Added TI recommendation to not solder the thermal pad to the PCB in the *Layout Guidelines* section	36

The datasheet number will be changing.

Device Family	Change From:	Change To:
TMP116, TMP116N	SBOS740	SBOS740A

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/TMP116

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

TMP116AIDRVR	TMP116AIDRVT	TMP116NAIDRVR	TMP116NAIDRVT

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products.